

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}^{(1)}$	3 A	$T_J = 25\text{ }^{\circ}\text{C}$	0.525	V
		6 A		0.68	
		3 A	$T_J = 125\text{ }^{\circ}\text{C}$	0.43	
		6 A		0.57	
Maximum reverse leakage current	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{Rated } V_R$	2.0	mA
		$T_J = 100\text{ }^{\circ}\text{C}$		20	
		$T_J = 125\text{ }^{\circ}\text{C}$		35	
Maximum junction capacitance	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz) $25\text{ }^{\circ}\text{C}$		230	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		3.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μ s

Note(1) Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J ⁽¹⁾ , T _{Stg}		- 55 to 150	°C
Maximum thermal resistance, junction to lead	R _{thJL} ⁽²⁾	DC operation	12	°C/W
Maximum thermal resistance, junction to ambient	R _{thJA}		46	
Approximate weight			0.24	g
			0.008	oz.
Marking device		Case style SMC (similar to DO-214AB)	V34	

Notes(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB

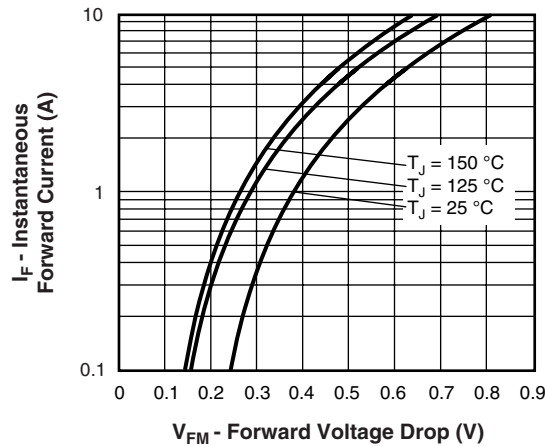


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

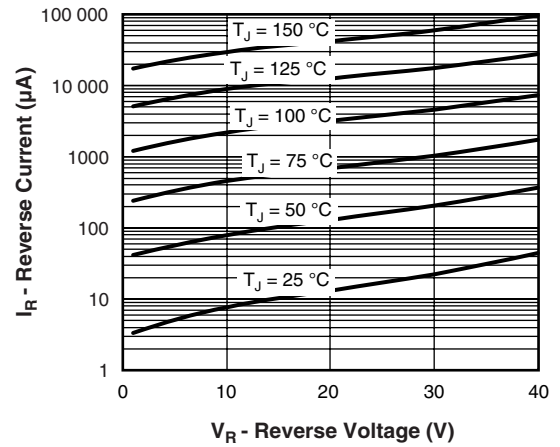


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

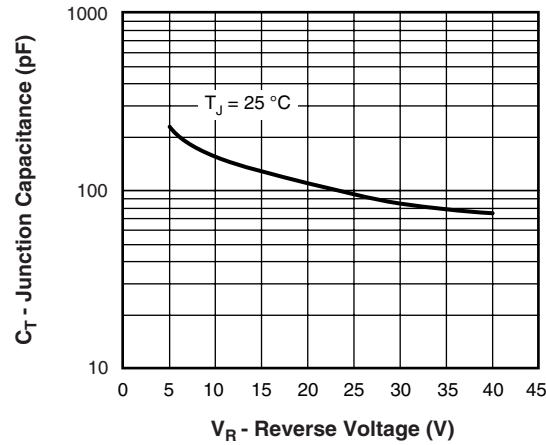


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

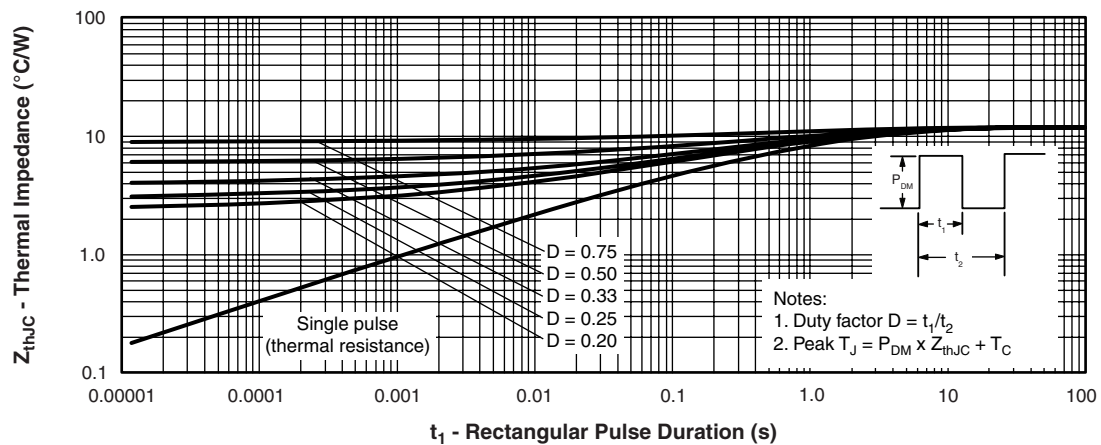


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

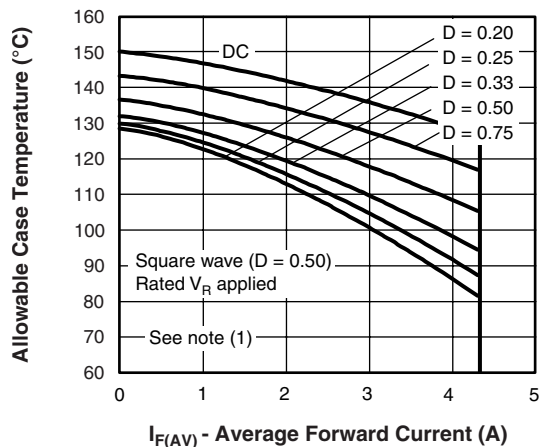


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

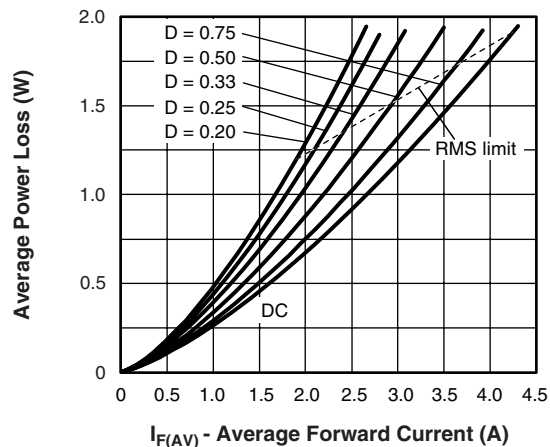


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

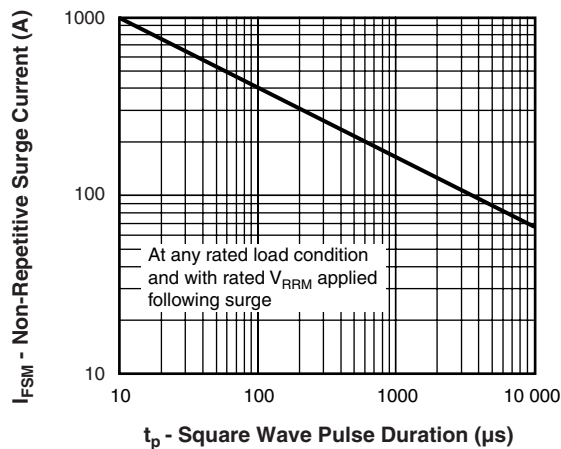


Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

**ORDERING INFORMATION TABLE**

Device code	MBR	S	3	40	TR	PbF
	1	2	3	4	5	6

- | | |
|----------|------------------------------------|
| 1 | - Schottky MBR series |
| 2 | - S = SMC |
| 3 | - Current rating (3 = 3 A) |
| 4 | - Voltage rating (40 = 40 V) |
| 5 | - TR = Tape and reel (3000 pieces) |
| 6 | - PbF = Lead (Pb)-free |

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95023
Part marking information	www.vishay.com/doc?95029
Packaging information	www.vishay.com/doc?95034
SPIICE model	www.vishay.com/doc?95366



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